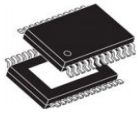


## Quad high-side smart power solid-state relay


**PowerSSO-24**

**Product status**

VNI4140K

VNI4140K-32

**Product label**


### Features

- Operating output current: 0.6 A (VNI4140K) or 1.0 A (VNI4140K-32) per channel
- Per channel short-circuit protection
- Per channel overtemperature protection
- Thermal case protection
- Not simultaneous channel reactivation at Thermal case reset
- All type of loads (resistive, capacitive, inductive load) are driven
- Loss of GND protection
- Undervoltage shutdown with hysteresis
- Overvoltage protection ( $V_{CC}$  clamping)
- Very low supply current
- Per channel open drain thermal fault pins
- 5 V and 3.3 V compatible I/Os
- Fast demagnetization of inductive loads
- Designed to meet IEC61131-2, IEC61000-4-4, and IEC61000-4-5
- ESD according to IEC 61000-4-2 up to  $\pm 25$  kV

### Applications

- Programmable logic control
- Industrial PC peripheral input/output
- Numerical control machines

### Description

The **VNI414K** (for loads up to 0.6 A) and **VNI4140K-32** (for loads up to 1.0 A) are monolithic 4-channel drivers featuring very low  $R_{DS(on)}$  and per-channel diagnostic. The ICs, realized in STMicroelectronics™ VIPower™ technology, are intended to drive any kind of load with one side connected to ground.

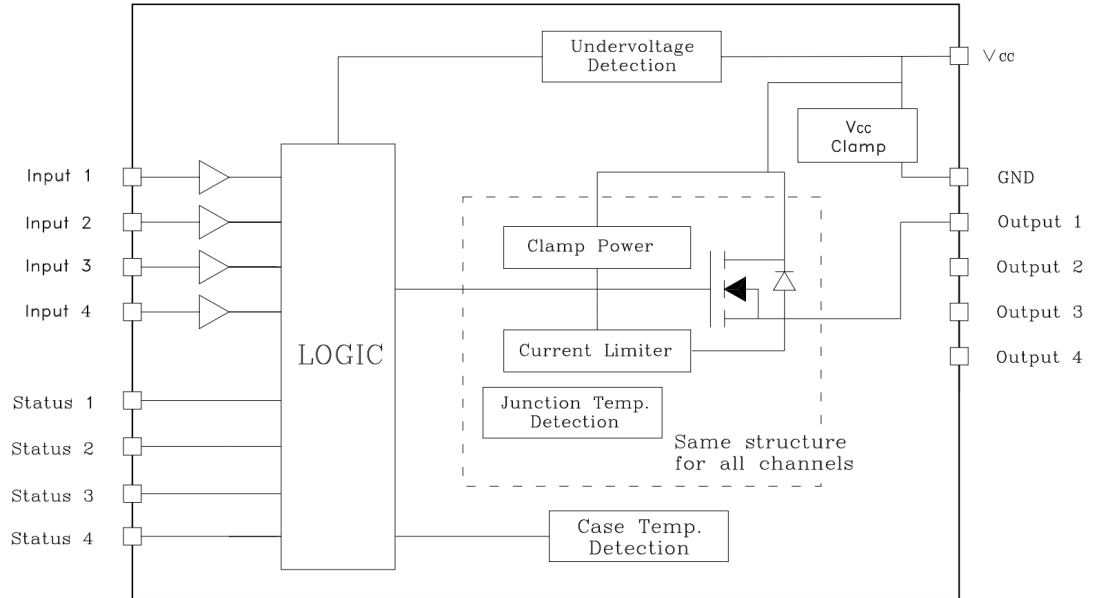
Active channel current limitation combined with thermal shutdown, independent for each channel, and automatic restart, protect the device against overload.

A channel in an overload condition overheats and turns OFF and back ON automatically in order to maintain its junction temperature between  $T_{TSD}$  and  $T_R$ . If this condition makes case temperature reach  $T_{CSD}$ , the overloaded channel is turned OFF and restarts only when case temperature has decreased down to  $T_{CR}$ . In case of more than one channel in overload, restart of the overloaded channels is not simultaneous, in order to avoid high peak current from the supply. Non-overloaded (non-overheated) channels continue operating normally.

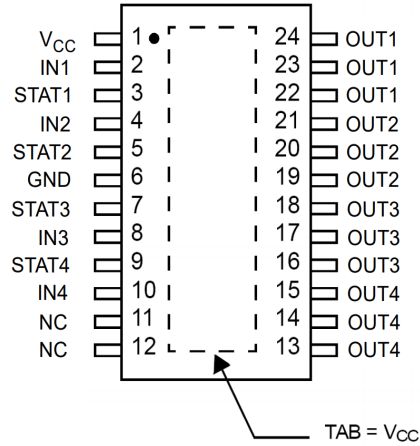
The four open drain  $STATUS_x$  output pins indicate per-channel overtemperature conditions.

# 1 Block diagram

Figure 1. Block diagram



## 2 Pin connection

**Figure 2. Pin connection (top view)**

**Table 1. Pin description**

Pin	Name	Type	Description
1, TAB	VCC	Supply	IC supply voltage.
2	IN1	Logic input	Channel 1 input, 3.3 V CMOS/TTL compatible.
3	STAT1	Output/Open Drain	Channel 1 overtemperature status (active low).
4	IN2	Logic input	Channel 2 input, 3.3 V CMOS/TTL compatible.
5	STAT2	Output/Open Drain	Channel 2 overtemperature status (active low).
6	GND	Ground	Device ground connection.
7	STAT3	Output/Open Drain	Channel 3 overtemperature status (active low).
8	IN3	Logic input	Channel 3 input, 3.3 V CMOS/TTL compatible.
9	STAT4	Output/Open Drain	Channel 4 overtemperature status (active low).
10	IN4	Logic input	Channel 4 input, 3.3 V CMOS/TTL compatible.
11, 12	NC	-	Not connected.
13, 14, 15	OUT4	Output	Channel 4 power stage output, internally protected.
16, 17, 18	OUT3	Output	Channel 3 power stage output, internally protected.
19, 20, 21	OUT2	Output	Channel 2 power stage output, internally protected.
22, 23, 24	OUT1	Output	Channel 1 power stage output, internally protected.

### 3 Maximum ratings

**Table 2. Absolute maximum ratings**

Symbol	Parameter	Value	Unit
V <sub>CC</sub>	Power supply voltage	-0.3 to 41	V
I <sub>GND</sub>	DC ground reverse current	-250	mA
I <sub>OUT</sub>	DC output current	Internally limited <sup>(1)</sup>	A
I <sub>R</sub>	DC reverse output current (per channel)	-5	A
I <sub>IN</sub>	Input pin current (per channel)	+/-10	mA
V <sub>IN</sub>	Input pin voltage	+V <sub>CC</sub>	V
V <sub>STAT</sub>	Status pin voltage	+V <sub>CC</sub>	V
I <sub>STAT</sub>	Status pin current (per pin)	+/-10	mA
V <sub>ESD</sub>	Electrostatic discharge (R = 1.5k Ω; C = 100 pF)	2000	V
E <sub>AS</sub> <sup>(2)</sup>	Single channel/single pulse avalanche energy @T <sub>amb</sub> = 125 °C, I <sub>OUT</sub> = 0.5 A	5	J
P <sub>TOT</sub>	Power dissipation at T <sub>C</sub> = 25 °C	Internally limited <sup>(1)</sup>	W
T <sub>J</sub>	Junction operating temperature	Internally limited <sup>(1)</sup>	°C
T <sub>STG</sub>	Storage temperature	-55 to 150	°C

1. Protection functions are intended to avoid IC damage in fault conditions and are not intended for continuous operation. Continuous and repetitive operation of protection functions may reduce the IC lifetime.

2. Single pulse, not repetitive

**Table 3. Thermal data**

Symbol	Parameter	Value	Unit
R <sub>th(JC)</sub>	Thermal resistance junction-case <sup>(1)</sup>	2	°C/W
R <sub>th(JA)</sub>	Thermal resistance junction-ambient	See Figure 12	°C/W

1. per channel

## 4 Recommended operating conditions

Table 4. Input switching limits

Symbol	Parameter	Value	Unit
$f_{VIN(MAX)}$	Maximum input switching frequency	10	kHz

## 5 Electrical characteristics

10.5 V < V<sub>CC</sub> < 36 V; -40 °C < T<sub>J</sub> < 125 °C; unless otherwise specified

### 5.1 Power section

**Table 5. Power section**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V <sub>CC</sub>	Supply voltage		10.5		36	V
R <sub>DS(on)</sub>	ON-state resistance	I <sub>OUT</sub> = 0.5 A @T <sub>J</sub> = 25 °C			0.08	Ω
		I <sub>OUT</sub> = 0.5 A			0.14	
I <sub>S</sub>	V <sub>CC</sub> supply current	All channels in OFF-state		0.25		mA
		All channels in ON-state, V <sub>IN1..4</sub> = 5 V		2.4	4	mA
V <sub>CC clamp</sub>	Clamp on V <sub>CC</sub>	I <sub>S</sub> = 20 mA	41	45	52	V
V <sub>OUT(OFF)</sub>	OFF-state output voltage	V <sub>IN</sub> = 0 V, I <sub>OUT</sub> = 0 A			1	V
I <sub>OUT(OFF)</sub>	OFF-state output current	V <sub>IN</sub> = V <sub>OUT</sub> = 0 V	0		5	μA
I <sub>LGND</sub>	VNI4140K output current at GND disconnection	V <sub>CC</sub> = V <sub>IN</sub> = V <sub>STAT</sub> = V <sub>GND</sub> = 24 V; V <sub>OUT</sub> = 0 V			1.0	mA
	VNI4140K-32 output current at GND disconnection				0.5	mA
f <sub>CP</sub>	Charge pump frequency	Channel in ON-state <sup>(1)</sup>		1.45		MHz

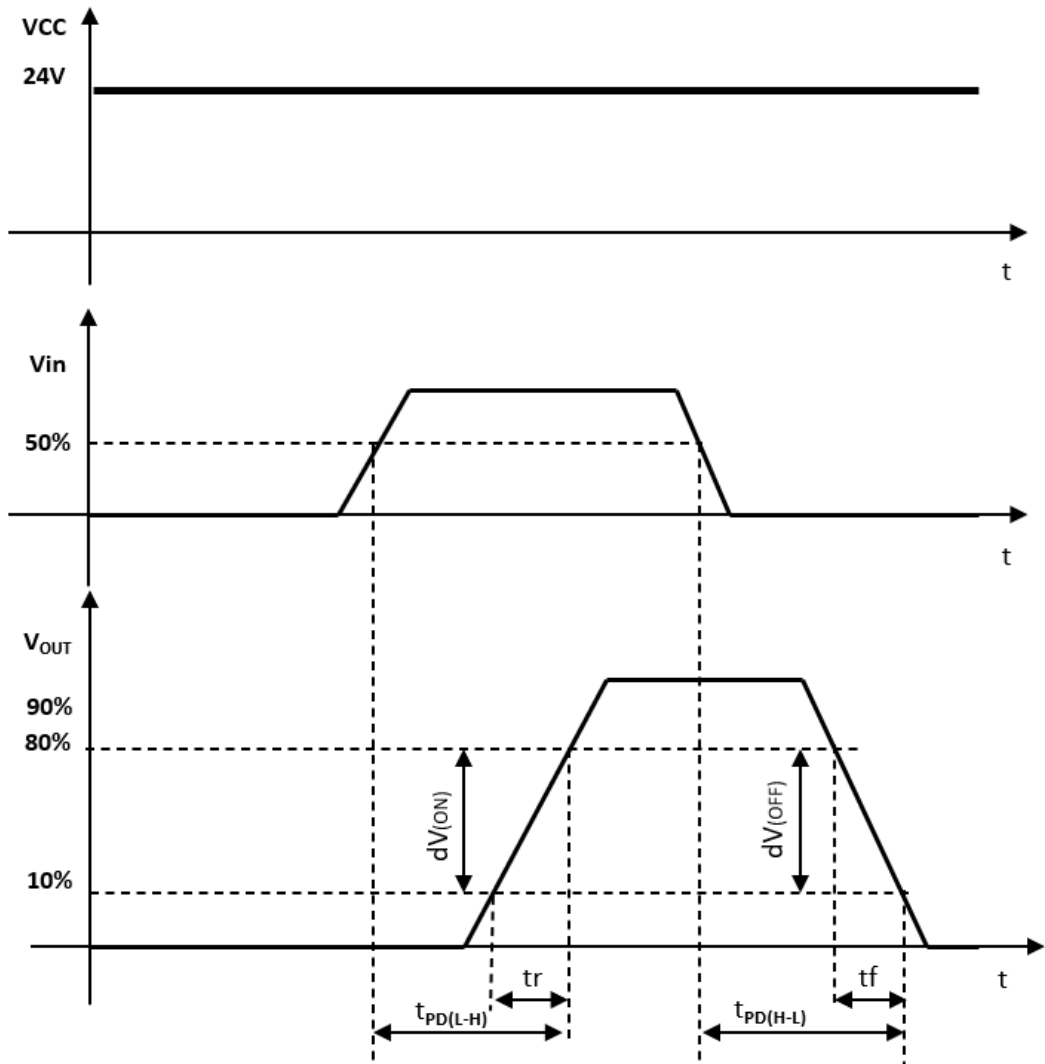
1. To cover EN55022 class A and class B normative.

### 5.2 Switching

**Table 6. Switching**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
t <sub>PD(L-H)</sub>	Turn-on delay time	V <sub>CC</sub> = 24 V, R <sub>L</sub> = 48 Ω, input rise time < 0.1 μs, see Figure 3	-	16	35	μs
t <sub>r</sub>	Rise time		-	8	25	μs
t <sub>PD(H-L)</sub>	Turn-off delay time		-	21	36	μs
t <sub>f</sub>	Fall time		-	4	12	μs
dV <sub>(ON)</sub> /dt <sub>r</sub>	Turn-on voltage slope		-	2	-	V/μs
dV <sub>(OFF)</sub> /dt <sub>f</sub>	Turn-off voltage slope		-	4	-	V/μs

Figure 3. Timing in normal operation



### 5.3 Logic inputs

Table 7. Logic inputs

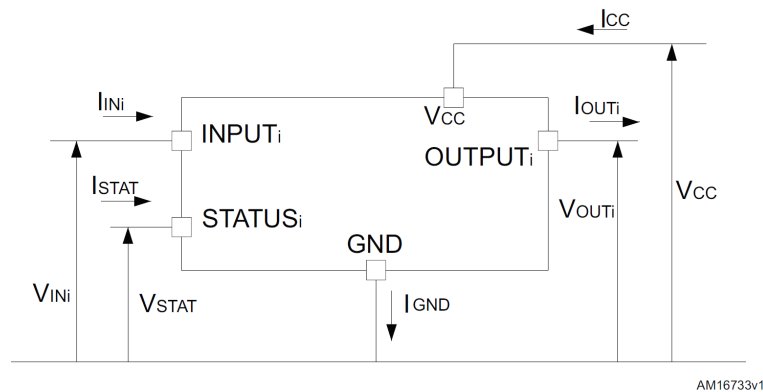
Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{IL}$	Input low level voltage				0.8	V
$V_{IH}$	Input high level voltage		2.20			V
$V_{I(HYST)}$	Input hysteresis voltage			0.15		V
$I_{IN}$	Input current	$V_{IN} = 15\text{ V}$			10	$\mu\text{A}$
		$V_{IN} = 36\text{ V}$			210	

## 5.4 Protection and diagnostic

**Table 8. Protection and diagnostic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{STAT}$	Status voltage output low	$I_{STAT} = 1.6 \text{ mA}$			0.6	V
$V_{USD}$	Undervoltage protection		7		10.5	V
$V_{USDHYS}$	Undervoltage hysteresis		0.4	0.5		V
$I_{PEAK}$	VNI4140K maximum DC output current	Dynamic load		1.3		A
	VNI4140K-32 maximum DC output current			1.6		
$I_{LIM}$	VNI4140K, DC short-circuit current	$V_{CC} = 24 \text{ V}, R_{LOAD} \leq 10 \text{ m}\Omega$	0.7	1.0	1.7	A
	VNI4140K-32, DC short-circuit current		1.1	1.5	2.6	
$I_{LSTAT}$	Status leakage current	$V_{CC} = V_{STAT} = 36 \text{ V}$		30		$\mu\text{A}$
$T_{TSD}$	Junction shutdown temperature		150	170	190	$^{\circ}\text{C}$
$T_R$	Junction reset temperature		135			$^{\circ}\text{C}$
$T_{HYST}$	Junction thermal hysteresis		7	15		$^{\circ}\text{C}$
$T_{CSD}$	Case shutdown temperature		125	130	135	$^{\circ}\text{C}$
$T_{CR}$	Case reset temperature		110			$^{\circ}\text{C}$
$T_{CHYST}$	Case thermal hysteresis		7	15		$^{\circ}\text{C}$
$V_{DEMAG}$	Output voltage at turn-OFF	$I_{OUT} = 0.5 \text{ A}; L_{LOAD} \geq 1 \text{ mH}$	$V_{CC} - 41$	$V_{CC} - 45$	$V_{CC} - 52$	V

## 5.5 Current and voltage conventions

**Figure 4. Current and voltage conventions**


AM16733v1



## 6 Truth table

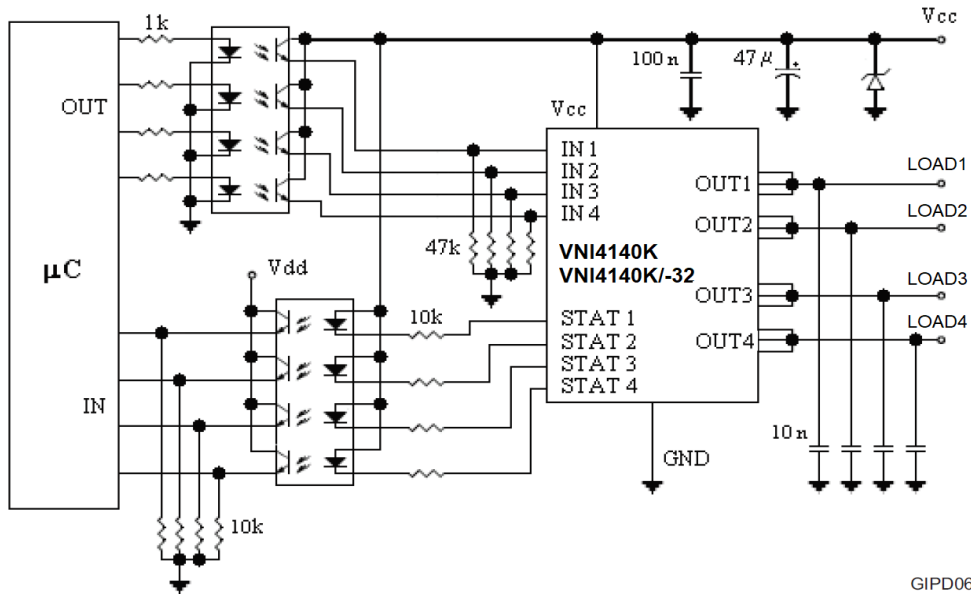
**Table 9. Truth table**

Condition	Input <sub>n</sub>	Output <sub>n</sub>	Status <sub>n</sub>
Normal operation	L	L	H
	H	H	H
Overtemperature	L	L	H
	H	L	L
Undervoltage	L	L	X
	H	L	X
Output overload (current limitation before overtemperature)	L	L	H
	H	X	H

*Note:* X = don't care

## 7 Typical application circuit

Figure 5. Typical application circuit

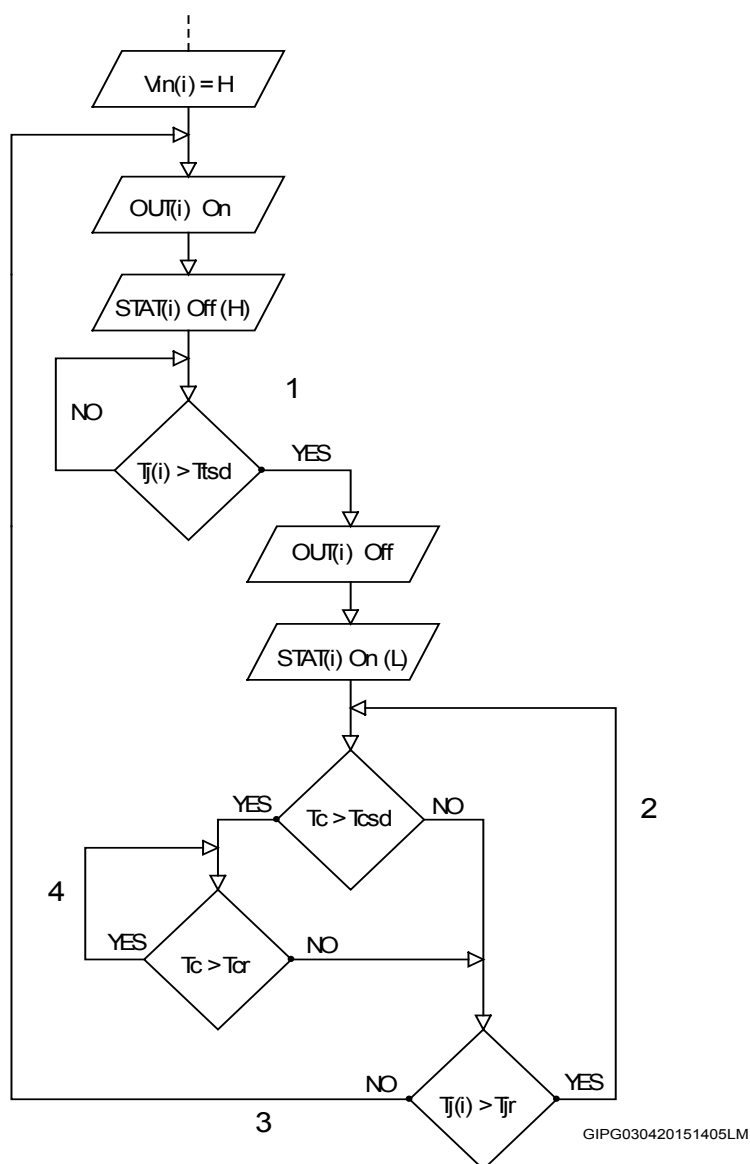


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## 8 Thermal management

The power dissipation in the IC is the main factor that sets the safe operating condition of the device in the application. Therefore, it must be considered very carefully. Furthermore, the available space on the PCB should be chosen considering the power dissipation. Heat sinking can be achieved using copper on the PCB with proper area and thickness. Two different protections have been implemented to guarantee safety of the device if it overheats due to an overloaded condition or high environment temperature. The following flowchart explains in detail this protection functionality.

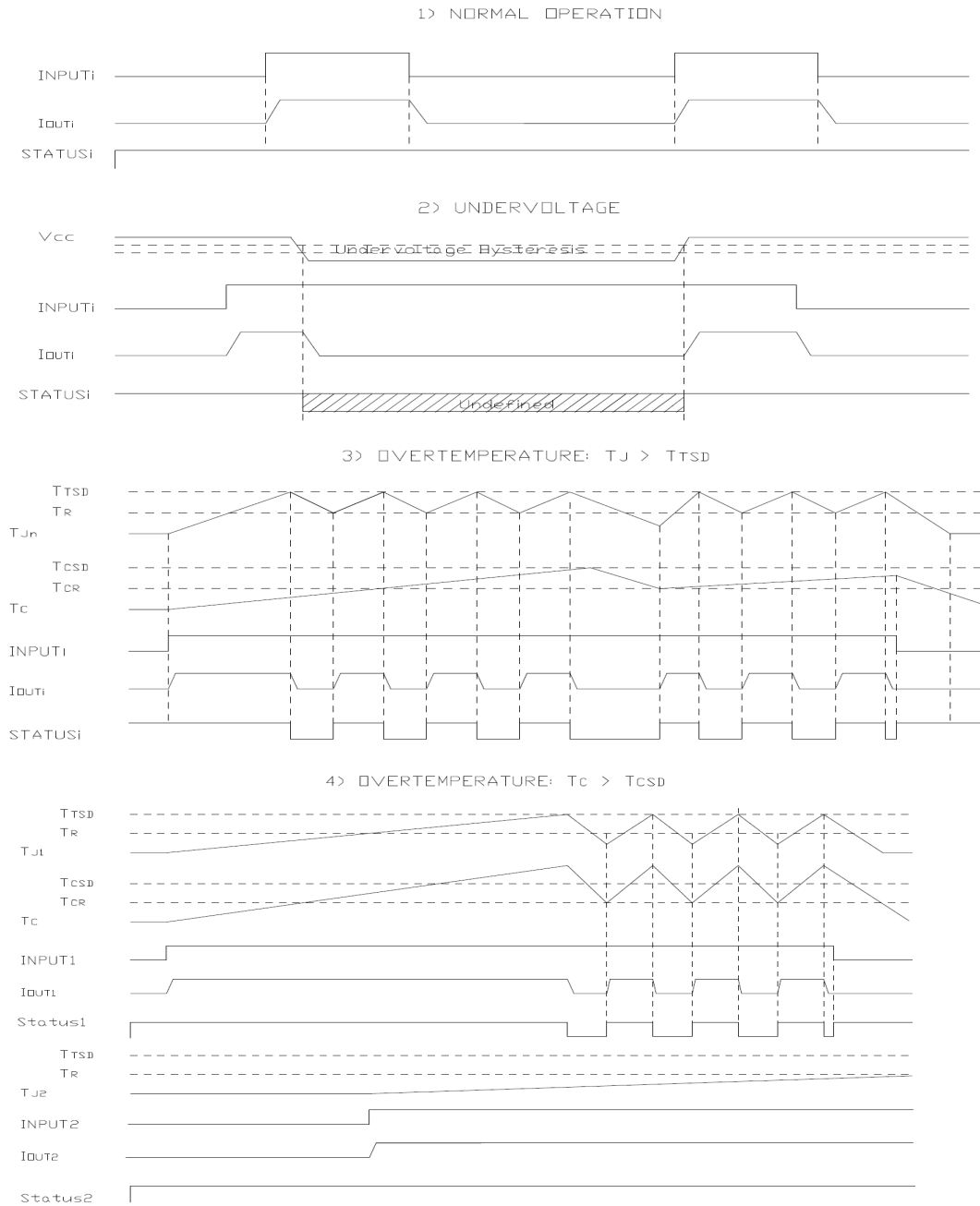
Figure 6. Thermal behavior



- Note:
- 1 Thermal shutdown
  - 2 Junction hysteresis
  - 3 Restore to idle condition
  - 4 Case hysteresis

## 9 Switching waveforms

Figure 7. Switching waveforms



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## 10 Pin function description

Figure 8. Input circuit

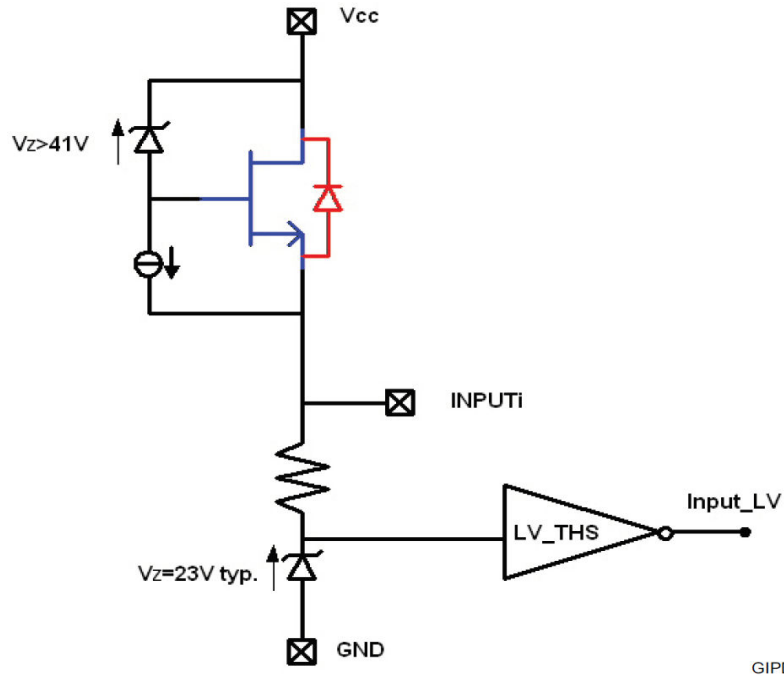


Figure 9. Status circuit

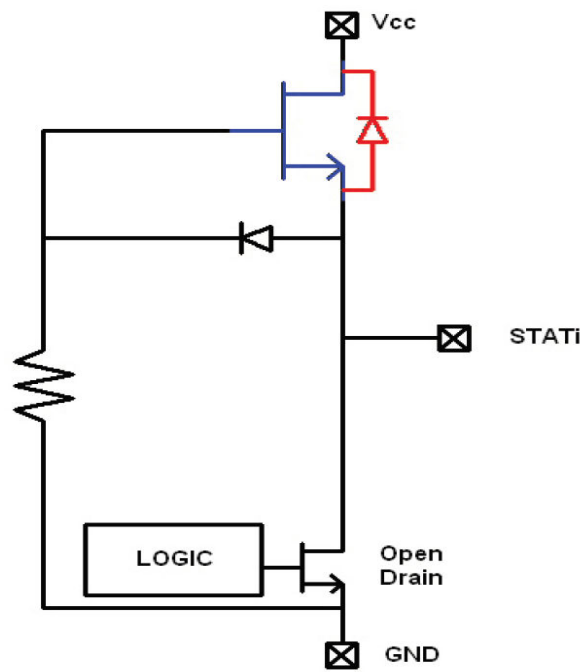
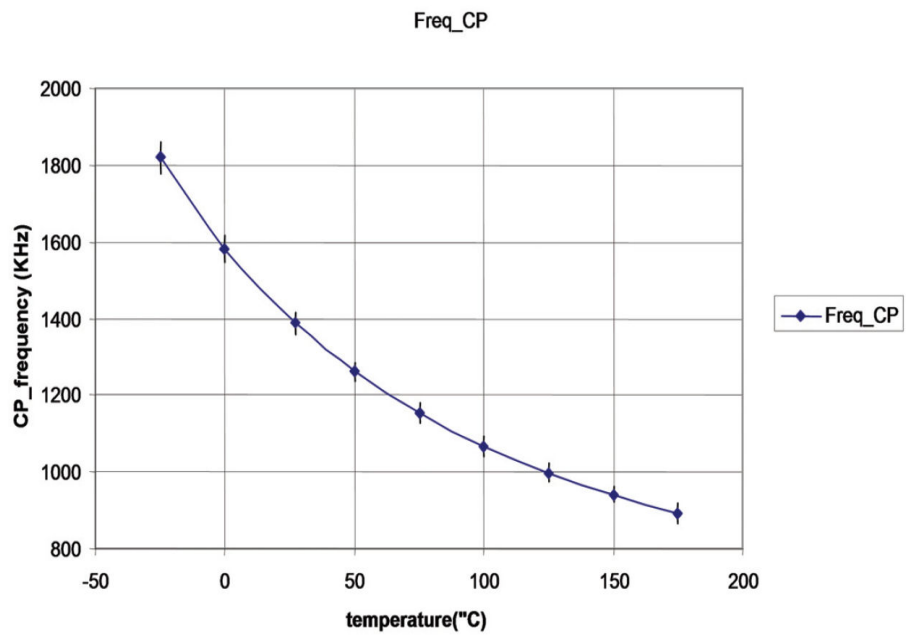


Figure 10. Charge pump switching frequency (typical) vs. temperature

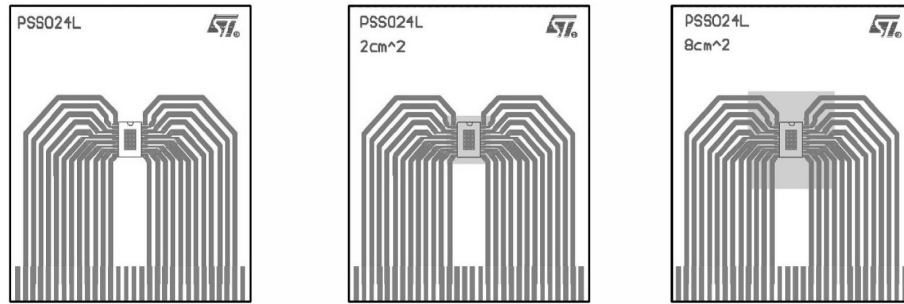


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## 11 Package and PCB thermal data

### 11.1 Thermal data

Figure 11. PCB for thermal tests



Layout condition of  $R_{TH}$  and  $Z_{TH}$  measurements (PCB: double layer, thermal vias, FR4 area = 77 mm x 86 mm, PCB thickness = 1.6 mm, Cu thickness = 70 mm (front and back side), copper areas: from minimum pad layout to 8 cm<sup>2</sup>).

Figure 12.  $R_{TH(JA)}$  vs. PCB copper area in open box free air condition (one channel ON)

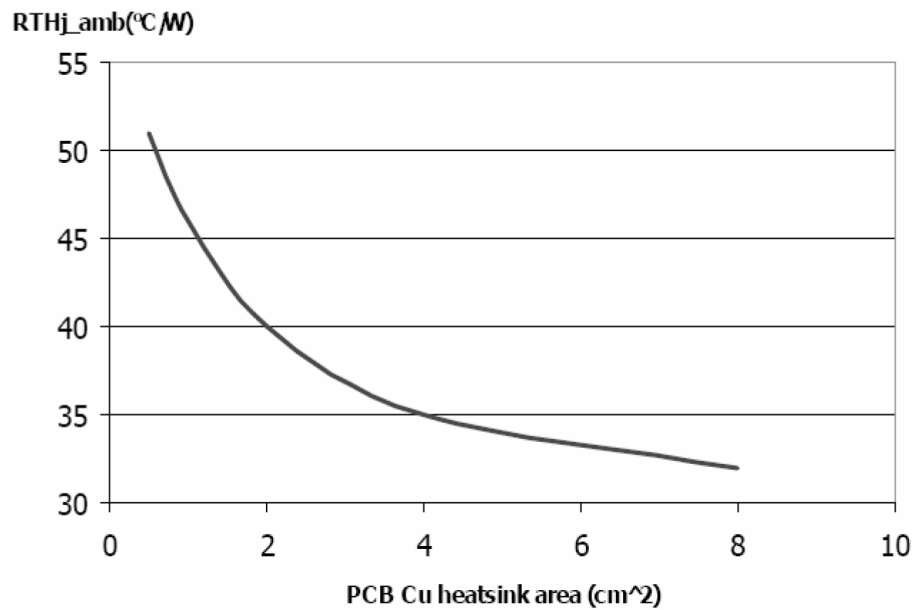
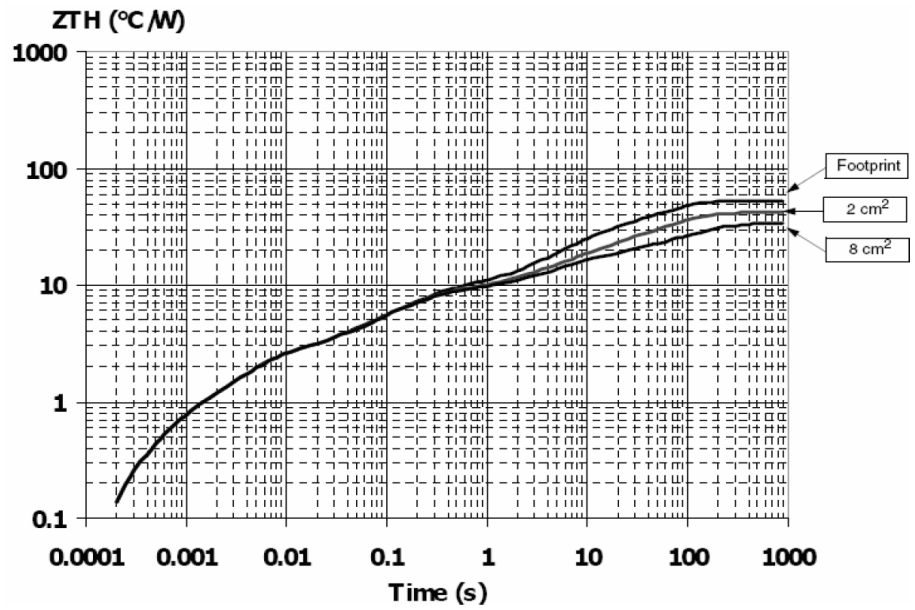


Figure 13. Thermal impedance junction-ambient single pulse (one channel ON)





## 12 Reverse polarity protection

Reverse polarity protection can be implemented on-board using two different solutions:

1. Placing a resistor ( $R_{GND}$ ) between IC GND pin and load GND
2. Placing a diode between IC GND pin and load GND

If option 1 is selected, the minimum resistance value has to be selected according to the following equation:

$$R_{GND} \geq V_{CC} / I_{GND}$$

where  $I_{GND}$  is the DC reverse ground pin current and can be found in Maximum ratings of this datasheet.

Power dissipated by  $R_{GND}$  (when  $V_{CC} < 0$ : during reverse polarity situations) is:

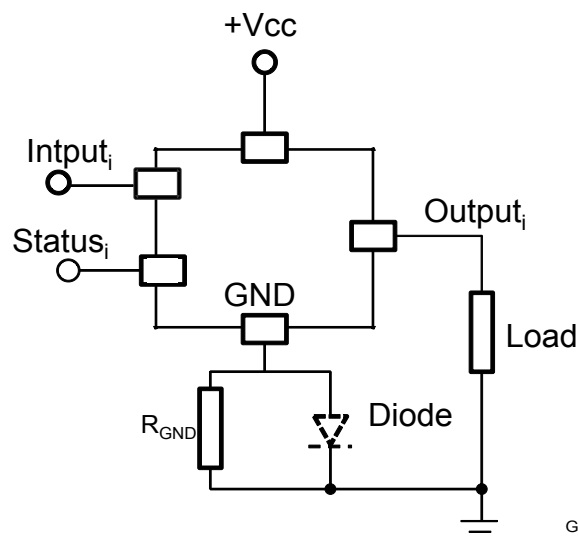
$$P_D = (V_{CC})^2 / R_{GND}$$

If option 2 is selected, the diode has to be chosen by taking into account  $V_{RRM} > |V_{CC}|$  and its power dissipation capability:

$$P_D \geq I_S * V_F$$

*Note:* In normal conditions (no reverse polarity), due to the diode, there is a voltage drop between GND of the device and GND of the system.

Figure 14. Reverse polarity protection



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This schematic can be used with any type of load.

## 13 Demagnetization energy

Figure 15. Single pulse (not repetitive) demagnetization energy vs. load current, typical values @  $T_{AMB} = 125\text{ }^{\circ}\text{C}$

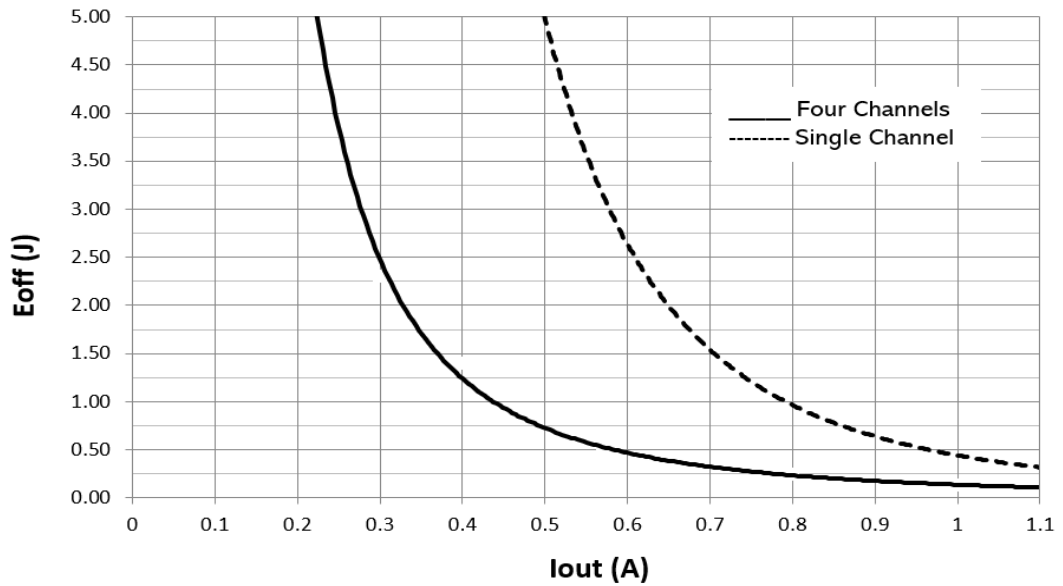
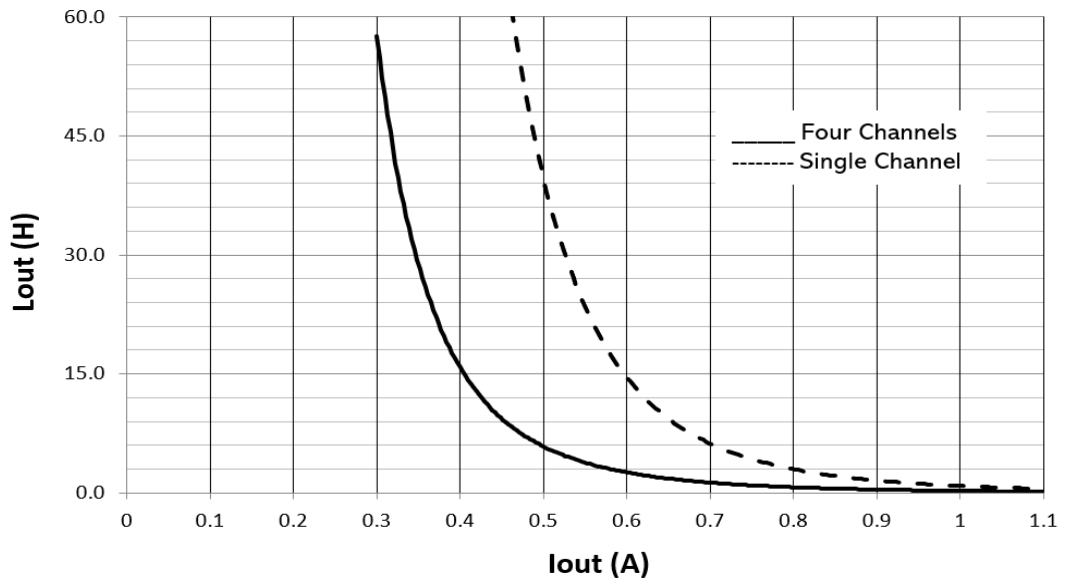


Figure 16. Single pulse (not repetitive) inductive load vs. load current, typical values @  $T_{AMB} = 125\text{ }^{\circ}\text{C}$

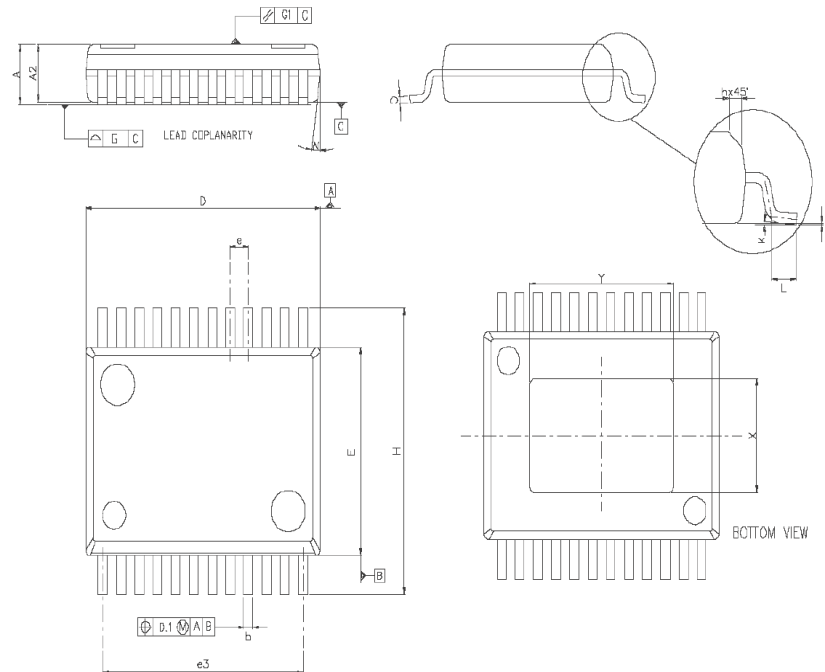


## 14 Package information

In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK is an ST trademark.

### 14.1 Package mechanical data

**Figure 17. PowerSSO-24 package dimensions [mm]**

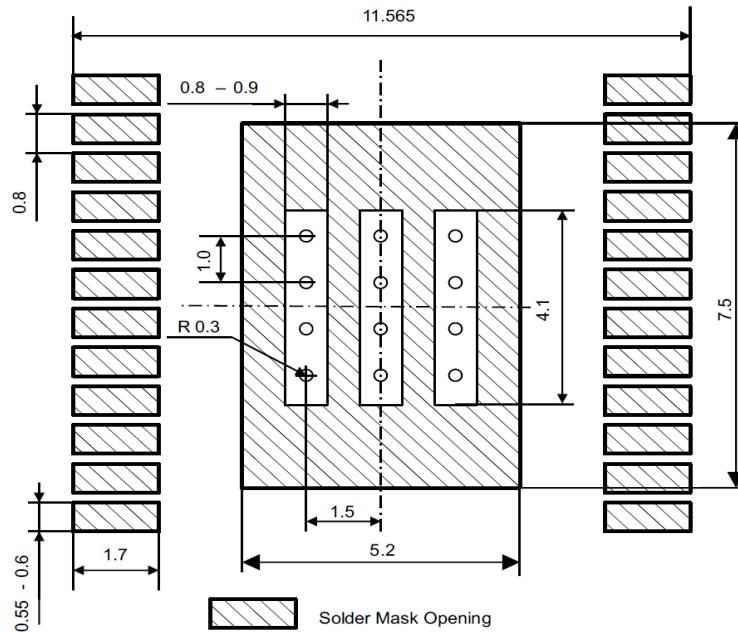


**Table 10. PowerSSO24, mechanical data**

Dim.	[mm]		
	Min.	Typ.	Max.
A	2.15		2.47
A2	2.15		2.40
a1	0		0.075
b	0.33		0.51
c	0.23		0.32
D	10.10		10.50
E	7.4		7.6
e		0.8	
e3		8.8	
G			0.1
G1			0.06
H	10.1		10.5
h			0.4
L	0.55		0.85

Dim.	[mm]		
	Min.	Typ.	Max.
N			10deg
X	4.1		4.7
Y	6.5		7.1

Figure 18. PowerSSO24 suggested footprint [mm]



STMicroelectronics is not responsible for any PCB related issues. The footprint shown in the above figure is a suggestion which might not be in line with the customer PCB supplier design rules.

## 14.2 PowerSSO24, packing information

Figure 19. PowerSSO-24 tube shipment (no suffix)

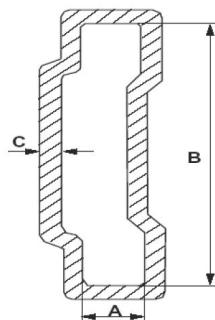


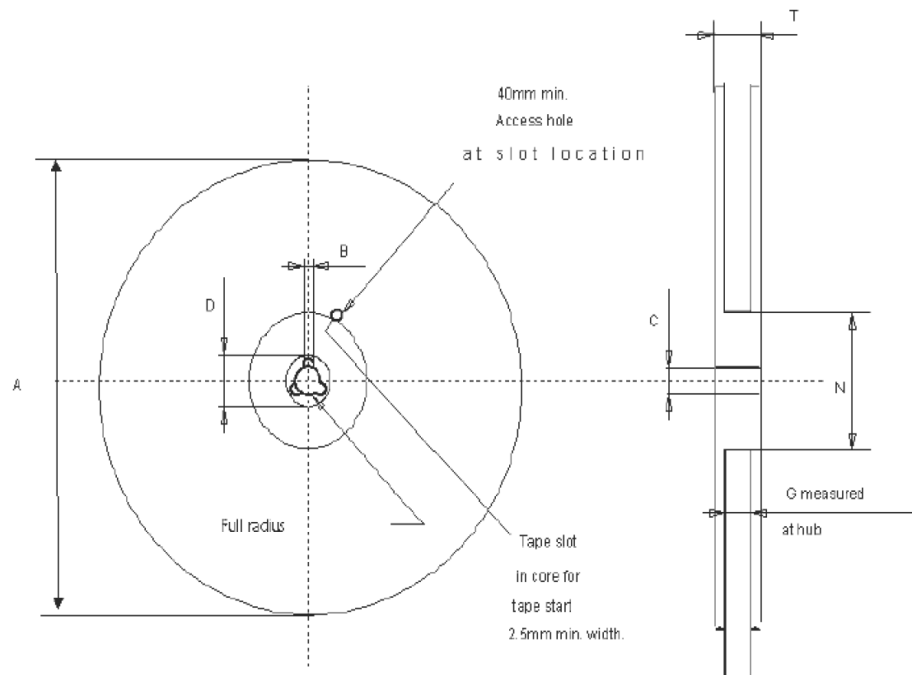
Table 11. PowerSSO24, tube shipment information

Description	Value
Base quantity	49
Bulk quantity	1225
Tube length ( $\pm 0.5$ )	532

Description	Value
A	3.5
B	13.8
C ( $\pm 0.1$ )	0.6

Note: All dimensions are in mm.

**Figure 20. PowerSSO24, reel shipment**



**Table 12. PowerSSO24, reel information**

Description	Value
Base quantity	1000
Bulk quantity	1000
A (max.)	330
B (min.)	1.5
C ( $\pm 0.2$ )	13
F	20.2
G ( $2 \pm 0$ )	24.4
N (min.)	100
T (max.)	30.4

Note: All dimensions are in mm.

Figure 21. PowerSSO24, tape drawings

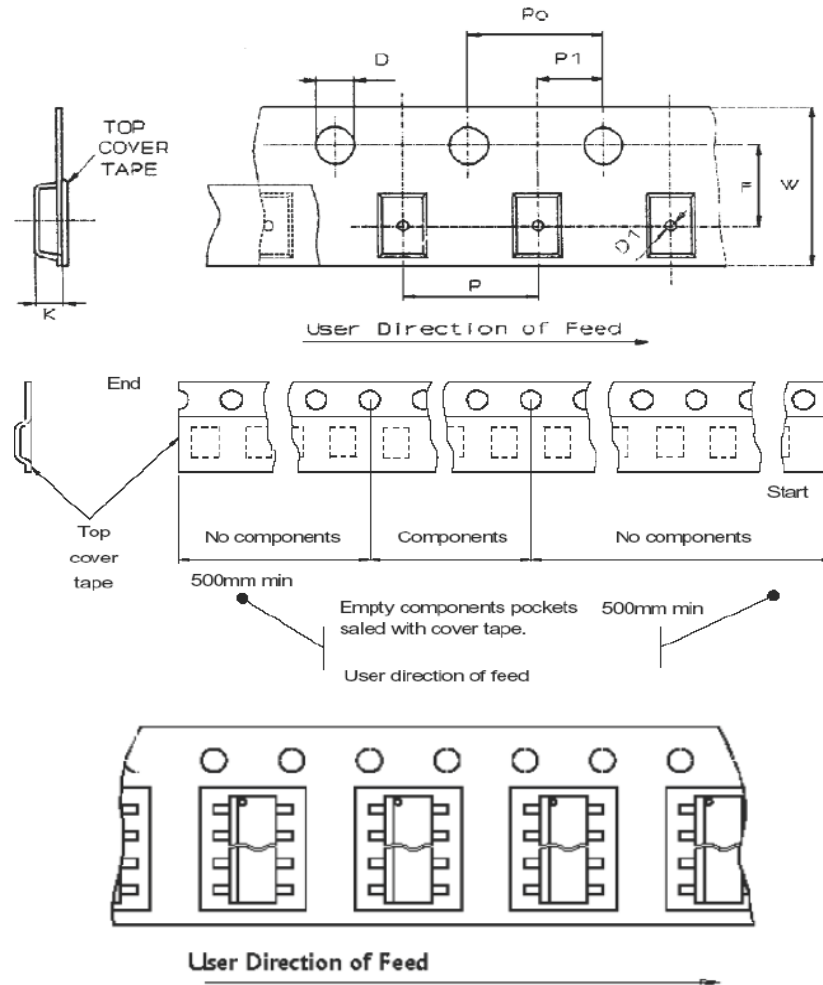


Table 13. PowerSSO24, tape dimension

Description	Symbol	Value
Tape width	W	24
Tape hole spacing	P0 ( $\pm 0.1$ )	4
Component spacing	P	12
Hole diameter	D ( $\pm 0.05$ )	1.55
Hole diameter	D1 (min.)	1.5
Hole position	F ( $\pm 0.1$ )	11.5
Compartment depth	K (max.)	2.85
Hole spacing	P1 ( $\pm 0.1$ )	2

Note: All dimensions are in mm.

Note: According to the Electronic Industries Association (EIA) standard 481 rev. A, Feb 1986.

## 15 Ordering information

Table 14. Order codes

Order code	Package	Package marking	Packaging
VNI4140K	PowerSSO-24	VNI4140K	Tube
VNI4140KTR			Tape and reel
VNI4140K-32		VNI4140K-32	Tube
VNI4140KTR-32			Tape and reel

## Revision history

**Table 15. Document revision history**

Date	Version	Changes
05-Oct-2021	1	Initial release.
22-Nov-2023	2	Changed $R_{DS(on)}$ test conditions for VNI4140K-32 in Table 5; some minor changes.
24-Jun-2024	3	Added footnote in Table 2; changed Figure 15; added Figure 16.



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